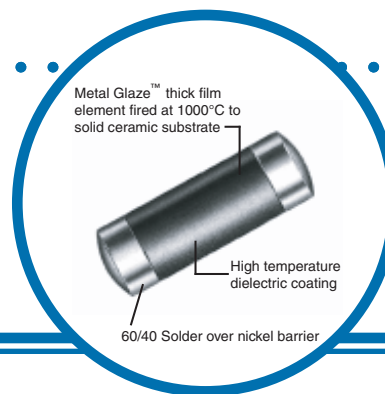


MRC Series

Metal Glaze™ High Power Density
Surface Mount Power Resistor



- 1/2 watt in 1/8 watt package
- 1 watt in 1/2 watt package (2010 footprint)
- MRC1/2: 0.05 Ω to 1.0 Ω
(contact factory for higher values)
- 150°C maximum operating temperature
- Superior surge handling capability



Environmental Data

Size Code ¹	Industry Footprint	IRC Type	Max. Power Rating	Working Voltage ²	Max. Voltage	Resistance Range (ohms) ³	Tolerance (±%) ³	TCR (ppm/°C) ³	Product Category
C	1206	MRC1/2	1/2W @ 70°C	200	400	0.1 to 0.99	1,2,5	100	Low Range
						1.0 to 10K	1,2,5	50,100	Standard
						20 to 10K	0.25, 0.5	50,100	Tight Tolerance
E	2010	MRC1	1W @ 70°C	350	700	0.05 to 0.099	2,5	200	Low Range
						0.10 to 1.0	1,2,5	100	Low Range

MRC Applications:

The MRC1/2 will dissipate 1/2 watt at 70°C on a 1206 footprint, while the MRC 1 will dissipate 1 watt at 70°C on a 2010 footprint. The MRC is recommended for applications where board real estate is a major concern. Due to high power density and superior surge handling capability, it is also recommended as a direct replacement on existing board designs where standard 1206 and 2010 resistors are marginal or failing.

Environmental Data

Characteristics	Maximum Change	Test Method
Temperature Coefficient	As specified	MIL-R-55342E Par 4.7.9 (-55°C + 125°C)
Thermal Shock	±(0.5% + 0.01Ω)	MIL-R-55342E Par 4.7.3 (-65°C + 150°C, 5 cycles)
Low Temperature Operation	±(0.25% + 0.01Ω)	MIL-R-55342E Par 4.7.4 (-65°C @ working voltage)
Short Time Overload	±(1.0% + 0.01Ω)	MIL-R-55342E Par 4.7.5 2.5 x √PxR for 5 seconds
High Temperature Exposure	±(0.5% + 0.01Ω)	MIL-R-55342E Par 4.7.6 (+150°C for 100 hours)
Resistance to Bonding Exposure	±(0.25% + 0.01Ω)	MIL-R-55342E Par 4.7.7 (Reflow soldered to board at 260°C for 10 seconds)
Solderability	95% minimum coverage	MIL-STD-202, Method 208 (245°C for 5 seconds)
Moisture Resistance	±(0.5% + 0.01Ω)	MIL-R-55342E Par 4.7.8 (10 cycles, total 240 hours)
Life Test	±(1.0% + 0.01Ω)	MIL-R-55342E Par 4.7.10 (2000 hours @ 70°C intermittent)
Terminal Adhesion Strength	±(1% + 0.01Ω) no mechanical damage	1200 gram push from underside of mounted chip for 60 seconds
Resistance to Board Bending	±(1% + 0.01Ω) no mechanical damage	Chip mounted in center of 90mm long board, deflected 5mm so as to exert pull on chip contacts for 10 seconds

General Note

IRC reserves the right to make changes in product specification without notice or liability. All information is subject to IRC's own data and is considered accurate at time of going to print.

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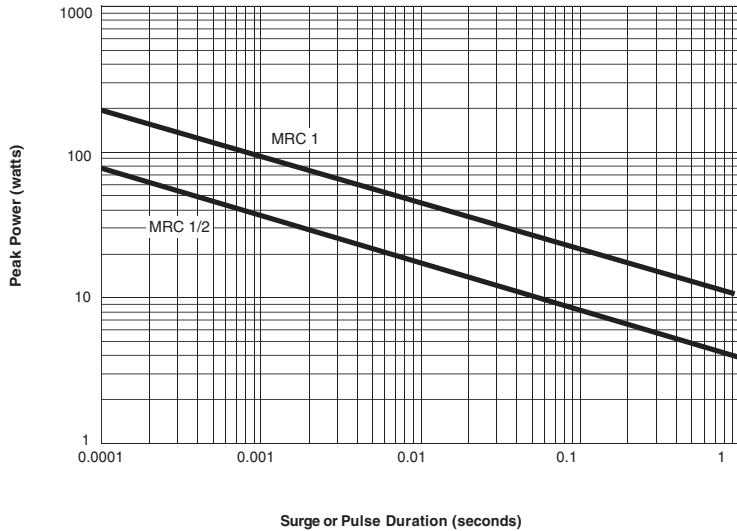
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MRC Series

Metal Glaze™ High Power Density
Surface Mount Power Resistor

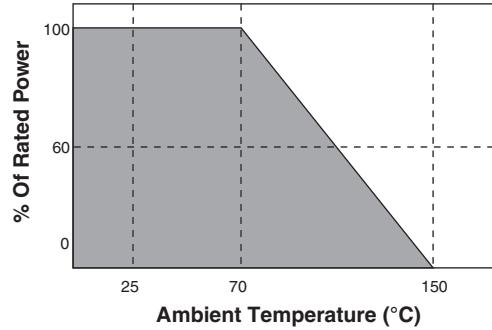


Repetitive Surge Curve



Note: Use for repetitive pulses where the average power dissipation is not to exceed the component rating at 70°C. Surge handling capacity for low-repetitive surges may be significantly greater than shown above. Contact factory for recommendations.

Power Derating Curve



Ordering Data

Sample Part No.	MRC1/2	100	1000	F	13	LF
IRC Type -	(MRC 1/2 & MRC 1)					
Temperature Coefficient	50 ppm, 100 ppm, 200 ppm					
Resistance Value	(100Ω and greater - First 3 significant figures plus 4th digit multiplier) Example: 100Ω = 1000, 1000Ω = 1001, 150,000Ω = 1503 (Less than 100Ω - "R" is used to designate decimal) Example: 51Ω = 51R0, 1Ω = 1R00, 0.25Ω = R250					
Tolerance	(C = 0.25%, D = 0.5%, F = 1.0%, G = 2.0%, J = 5.0%)					
Packaging Code*	(BLK = Bulk, 7 = 7" Reel, 13 = 13" Reel)					
RoHS Compliance	LF = RoHS compliant version					